

FDPF680N10T

N-Channel PowerTrench® MOSFET

100V, 12A, 68mΩ

Features

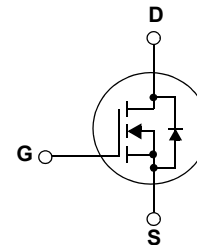
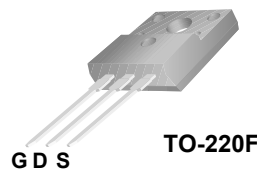
- $R_{DS(on)} = 54m\Omega$ (Typ.) @ $V_{GS} = 10V$, $I_D = 6A$
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- High Power and Current Handling Capability
- RoHS Compliant

Application

- DC to AC Converters / Synchronous Rectification

Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted*

| Symbol | Parameter | Ratings | Units |
|----------------|--|---|--------------------|
| V_{DSS} | Drain to Source Voltage | 100 | V |
| V_{GSS} | Gate to Source Voltage | ± 20 | V |
| I_D | Drain Current | -Continuous ($T_C = 25^\circ\text{C}$) | A |
| | | -Continuous ($T_C = 100^\circ\text{C}$) | |
| I_{DM} | Drain Current | - Pulsed (Note 1) | A |
| E_{AS} | Single Pulsed Avalanche Energy | (Note 2) | mJ |
| dv/dt | Peak Diode Recovery dv/dt | (Note 3) | V/ns |
| P_D | Power Dissipation | ($T_C = 25^\circ\text{C}$) | W |
| | | - Derate above 25°C | $W/^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ\text{C}$ |
| T_L | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | 300 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Ratings | Units |
|-----------------|---|---------|--------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 5.2 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 62.5 | |

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Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|-------------|---------|-----------|------------|----------|
| FDPF680N10T | FDPF680N10T | TO-220F | - | - | 50 |

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|--------|-----------|-----------------|------|------|------|-------|
|--------|-----------|-----------------|------|------|------|-------|

Off Characteristics

| | | | | | | |
|--------------------------------------|---|---|-----|-----|-----------|------------------|
| BV_{DSS} | Drain to Source Breakdown Voltage | $I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$, $T_C = 25^\circ\text{C}$ | 100 | - | - | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\mu\text{A}$, Referenced to 25°C | - | 0.1 | - | $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 100\text{V}$, $V_{GS} = 0\text{V}$ | - | - | 1 | μA |
| | | $V_{DS} = 100\text{V}$, $V_{GS} = 0\text{V}$, $T_C = 150^\circ\text{C}$ | - | - | 500 | |
| I_{GSS} | Gate to Body Leakage Current | $V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$ | - | - | ± 100 | nA |

On Characteristics

| | | | | | | |
|--------------|--------------------------------------|---|-----|-----|-----|------------------|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$ | 2.5 | 3.5 | 4.5 | V |
| $R_{DS(on)}$ | Static Drain to Source On Resistance | $V_{GS} = 10\text{V}$, $I_D = 6\text{A}$ | - | 54 | 68 | $\text{m}\Omega$ |
| g_{FS} | Forward Transconductance | $V_{DS} = 10\text{V}$, $I_D = 12\text{A}$ (Note 4) | - | 26 | - | S |

Dynamic Characteristics

| | | | | | | |
|--------------|-------------------------------|---|---|-----|------|----|
| C_{iss} | Input Capacitance | $V_{DS} = 50\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$ | - | 750 | 1000 | pF |
| C_{oss} | Output Capacitance | | - | 60 | 80 | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 25 | 40 | pF |
| $Q_{g(tot)}$ | Total Gate Charge | $V_{DS} = 80\text{V}$, $I_D = 12\text{A}$ $V_{GS} = 10\text{V}$ | - | 13 | 17 | nC |
| Q_{gs} | Gate to Source Gate Charge | | - | 4 | - | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | | - | 4 | - | nC |

(Note 4, 5)

Switching Characteristics

| | | | | | | |
|--------------|---------------------|--|---|----|----|----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 50\text{V}$, $I_D = 12\text{A}$ $V_{GS} = 10\text{V}$, $R_{GEN} = 10\Omega$ | - | 13 | 36 | ns |
| t_r | Turn-On Rise Time | | - | 19 | 48 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 18 | 46 | ns |
| t_f | Turn-Off Fall Time | | - | 6 | 22 | ns |

(Note 4, 5)

Drain-Source Diode Characteristics

| | | | | | | |
|-----------------|--|---|---|----|-----|----|
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 12 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 48 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} = 0V, I _{SD} = 12A | - | - | 1.3 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0V, I _{SD} = 12A dI _F /dt = 100A/μs (Note 4) | - | 29 | - | ns |
| Q _{rr} | Reverse Recovery Charge | | - | 35 | - | nC |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 0.7\text{mH}$, $I_{AS} = 12\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 12\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

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Typical Performance Characteristics

Figure 1. On-Region Characteristics

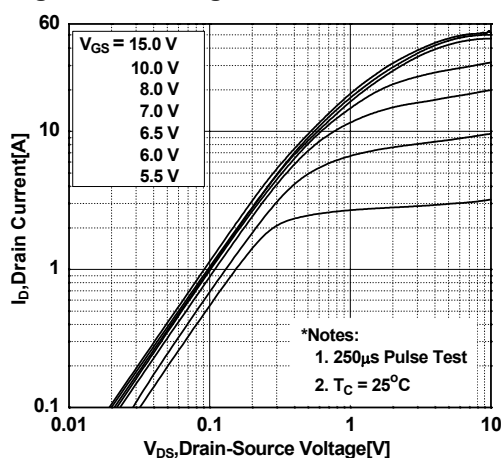


Figure 2. Transfer Characteristics

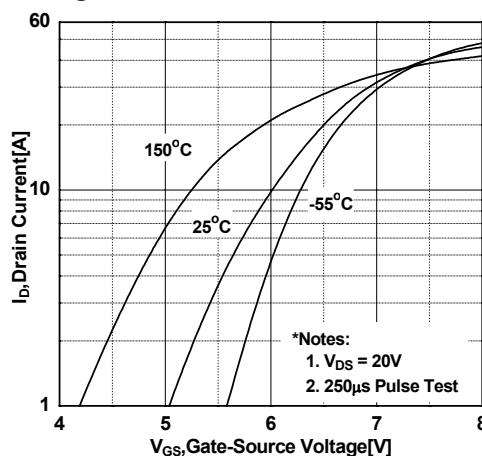


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

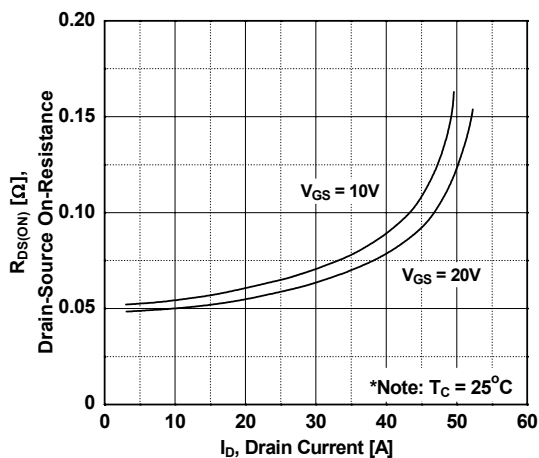


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

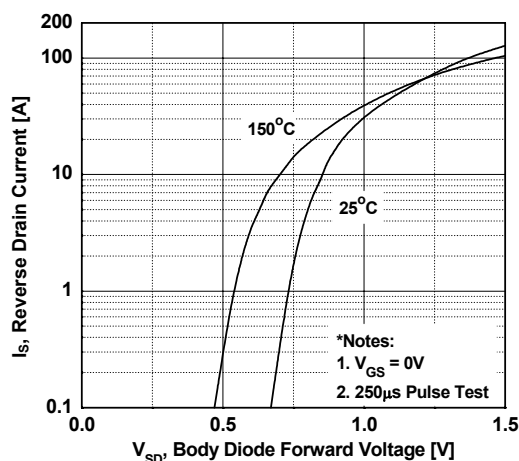


Figure 5. Capacitance Characteristics

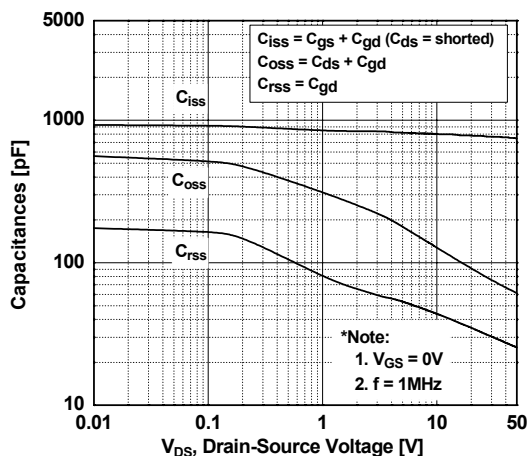
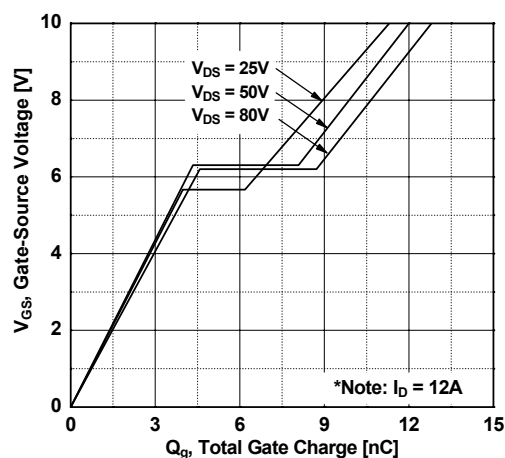


Figure 6. Gate Charge Characteristics



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Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

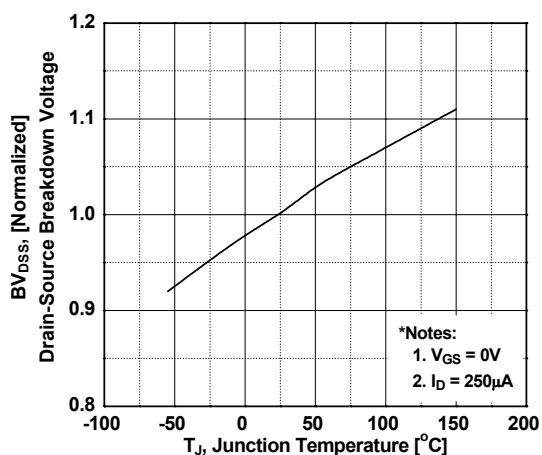


Figure 8. On-Resistance Variation vs. Temperature

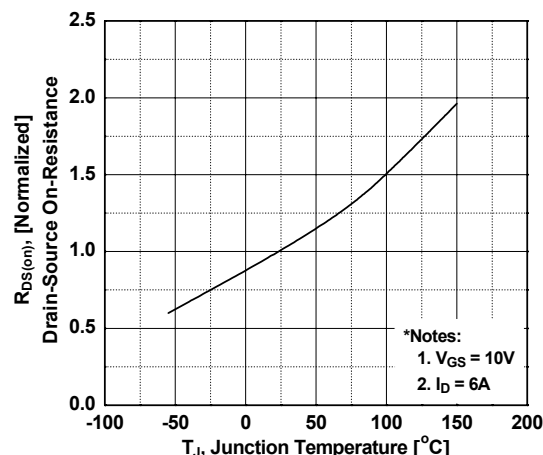


Figure 9. Maximum Safe Operating Area

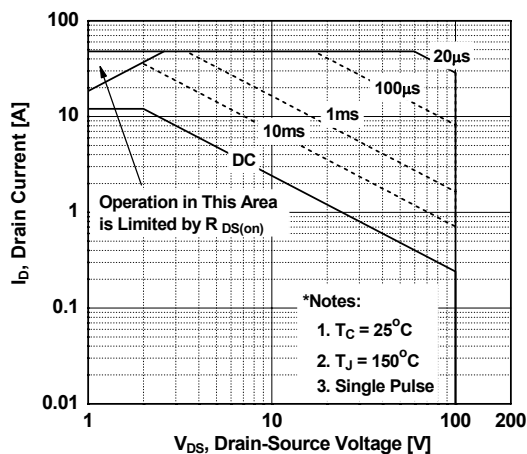


Figure 10. Maximum Drain Current vs. Case Temperature

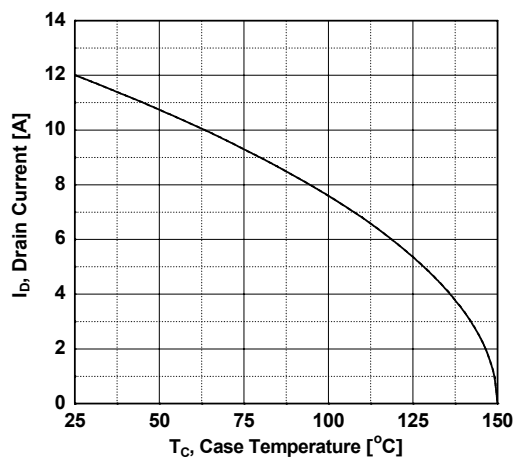
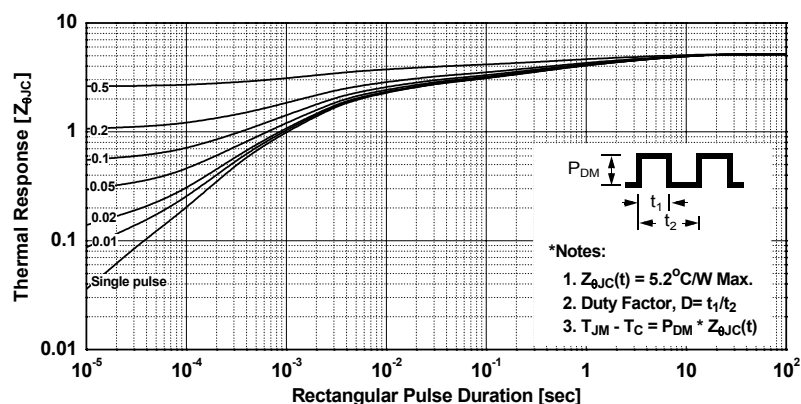
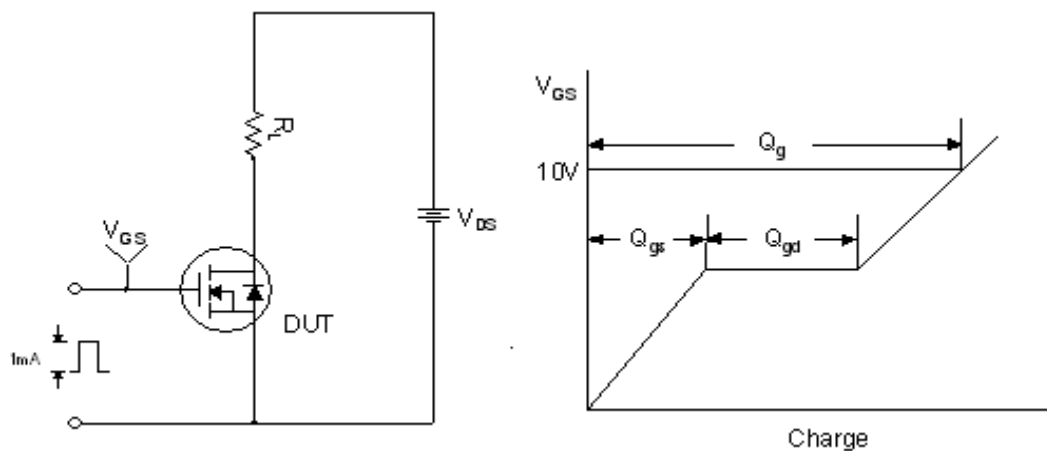


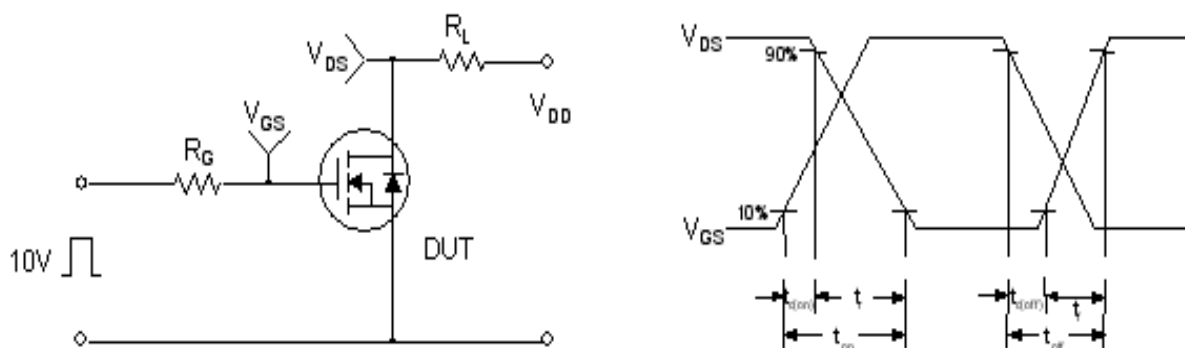
Figure 11. Transient Thermal Response Curve



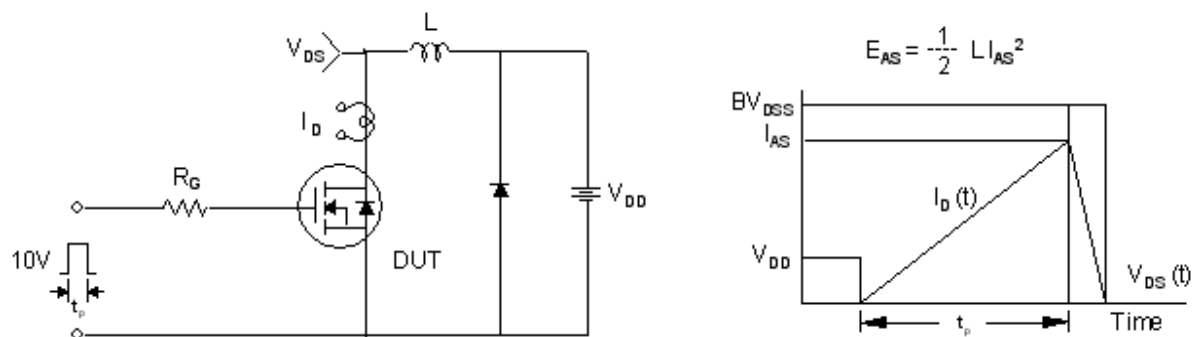
Gate Charge Test Circuit & Waveform



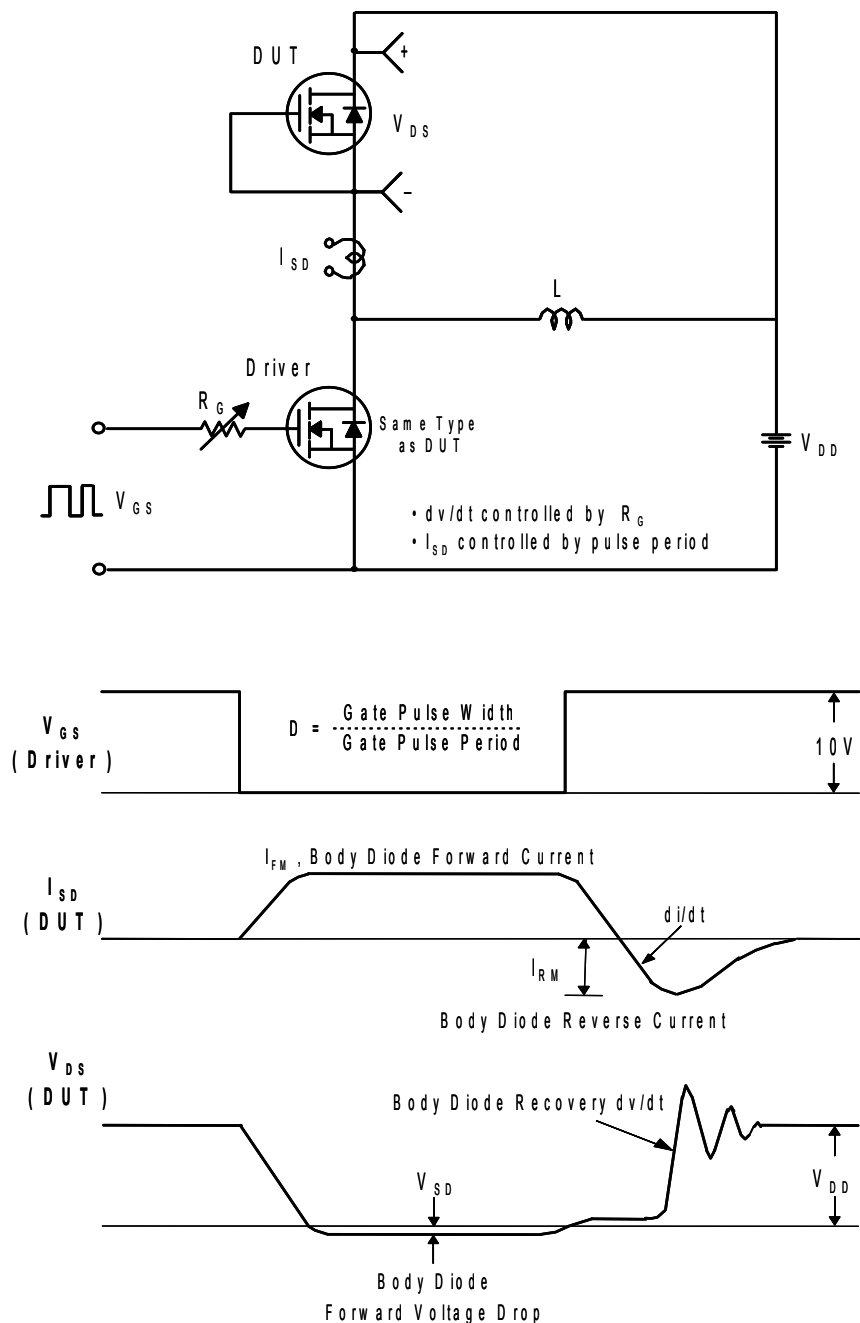
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

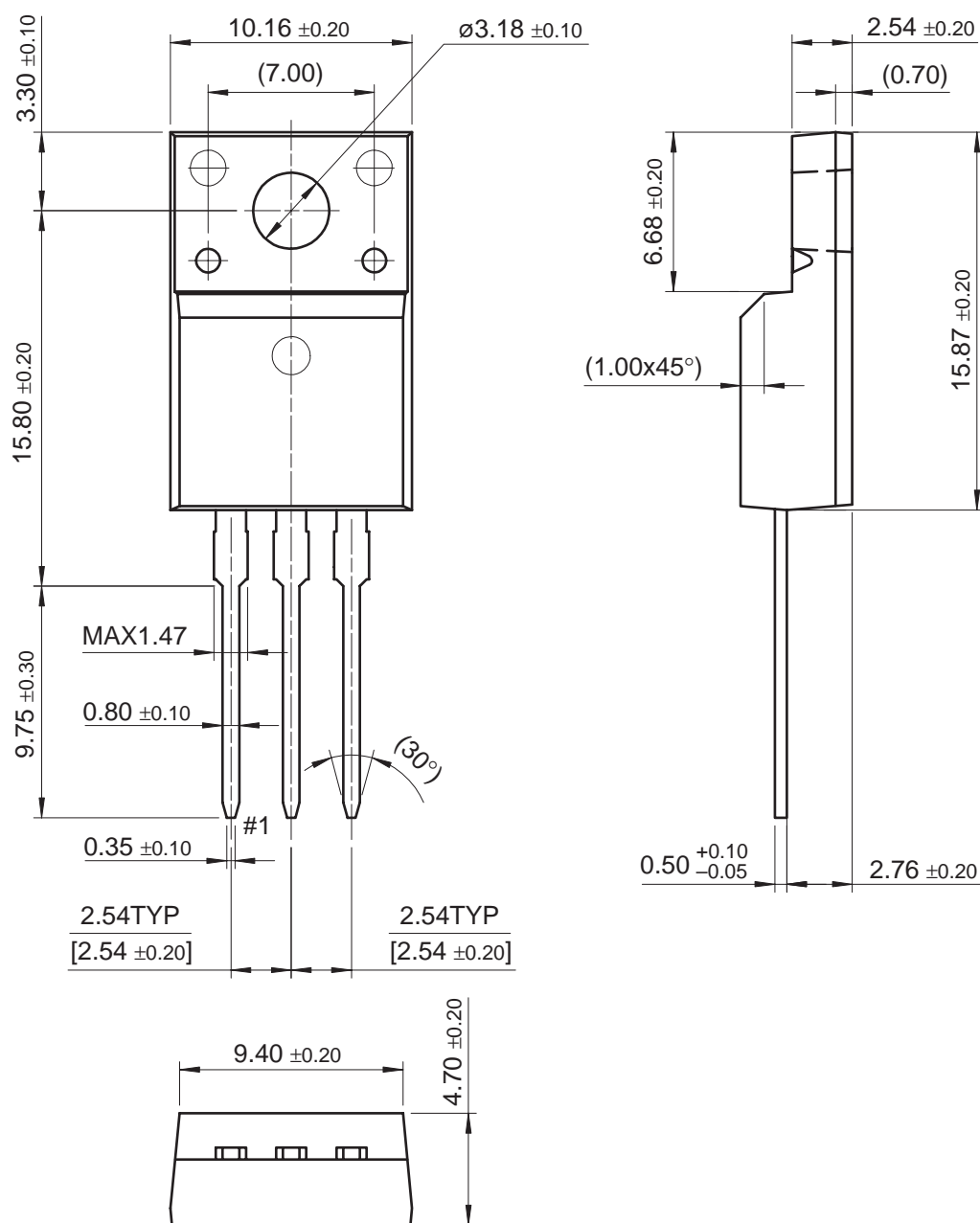


Peak Diode Recovery dv/dt Test Circuit & Waveforms



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Mechanical Dimensions

TO-220F



Dimensions in Millimeters

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